

Abstract

Disclosed is a method for depositing a thickfilm dielectric on a substrate. The method commences with the deposition of a first layer of
5 thickfilm dielectric on the substrate, followed by an air drying of the first layer to allow solvents to escape, thereby increasing the porosity of the first layer. The first layer is then oven dried. Thereafter, additional layers of thickfilm dielectric are deposited on top of the first layer, with each layer being oven dried after it is deposited. The deposited layers are then fired.